

RELIABILITY REPORT
FOR
MAX3058ASA+
PLASTIC ENCAPSULATED DEVICES

April 27, 2011

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX3058ASA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX3058/MAX3059 interface between the controller area network (CAN) protocol controller and the physical wires of the bus lines in a CAN. They are primarily intended for printer and telecom backplane applications requiring data rates up to 1Mbps. These devices provide differential transmit capability to the bus and differential receive capability to the CAN controller. The MAX3058 output common-mode range is from -7V to +12V. The MAX3059 output common-mode range is from 0V to VCC. The MAX3059 contains an internal switch termination resistor that makes it ideal for JetLink[®] applications. The MAX3058 features four different modes of operation: high speed, slope control, standby, and shutdown. The MAX3059 features three different modes of operation: high speed, slope control, and shutdown. High-speed mode allows data rates up to 1Mbps. In slope-control mode, the slew rate may be optimized for data rates up to 500kbps, so the effects of EMI are reduced, and unshielded twisted or parallel cable can be used. In standby mode, the transmitters are shut off and the receivers are put into low-current mode. In shutdown mode, the transmitter and receiver are switched off. The MAX3058/MAX3059 are available in an 8-pin SO package and are specified over the -40°C to +125°C temperature range.

II. Manufacturing Information

A. Description/Function:	5V, 1Mbps, Low Supply Current CAN Transceivers
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	September 26, 2003

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0590
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	132°C/W
M. Multi Layer Theta Jc:	38°C/W

IV. Die Information

A. Dimensions:	70 X 45 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 96 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 11.5 \times 10^{-9}$$

$$\lambda = 11.5 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot SGS0CQ003B D/C 0426)

The RT72 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX3058ASA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C	DC Parameters	48	0	SGS0CQ003B, D/C 0426
	Biased Time = 192 hrs.	& functionality	48	0	SGS0BU002C, D/C 0332

Note 1: Life Test Data may represent plastic DIP qualification lots.